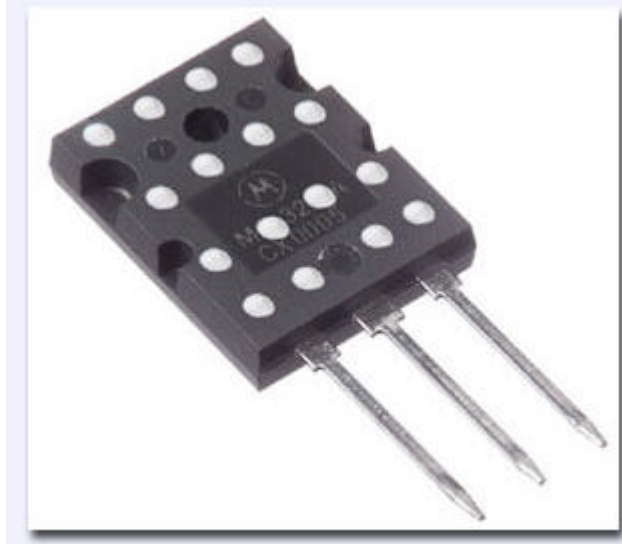


**"Tacky2" Hot Melt 71°C**



**Advantages:**

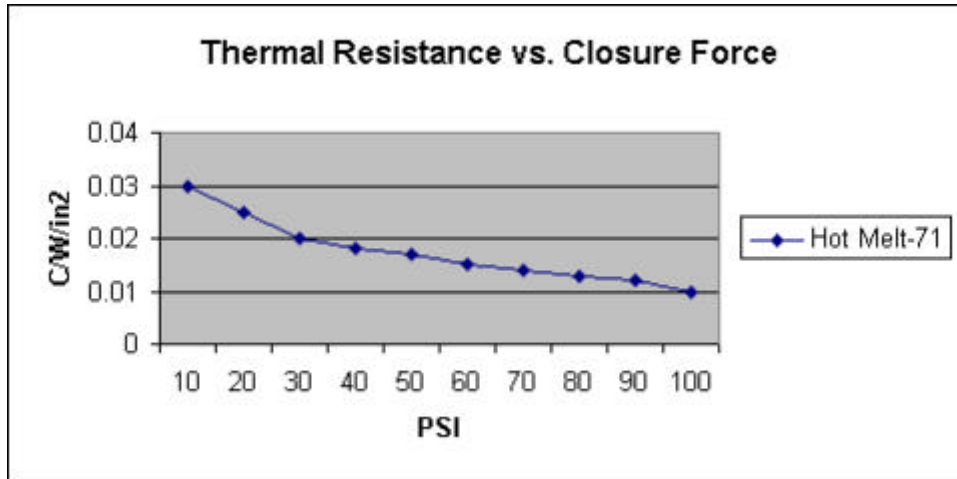
- ?? Thermal Resistance 0.03 C/W/in<sup>2</sup> at 10 psi
- ?? Phase Change Temperature 71°C
- ?? Naturally tacky on both sides both before and after reflow
- ?? Manufacturing Friendly - easy to use
- ?? Thixotropic and won't flow from gaps
- ?? Thermoplastic reversible adhesive bond
- ?? Use for creating thermal interface patterns on component and heat sinks
- ?? Use for conformal coating, gap filling, potting

**Description:**

"Tacky2" Hot Melt material can be applied to surfaces using manual or automatic dispensing equipment, by injection molding, or by screen-printing, in any required pattern. Once the Hot Melt material has been applied to a surface and recooled to the solid state, it is naturally adhesive at room temperature. For example, the transistor in the above picture can be pressed against a heat sink, at room temperature and will adhere to it. Adhesive strength is 25 psi. Note that this material is not electrically conductive, but contains nothing to prevent component to heat sink electrical/mechanical contact. Special "Tacky2" materials are available which do prevent electrical/mechanical contact between the heat sink and component. When "Tacky2" material is reheated above its phase change temperature the adhesive bond is broken and the component is easily removed. "Tacky2" is thermoplastic. Unlike thermal epoxies, which are thermosetting, "Tacky2" can be melted and re-solidified an unlimited number of times. Unlike messy epoxy thermosetting materials, "Tacky2" does not require long cure times. You only need to elevate the temperature of the "Tacky2" long enough for it to flow into the surface pores of component and heat sink (or other surface).

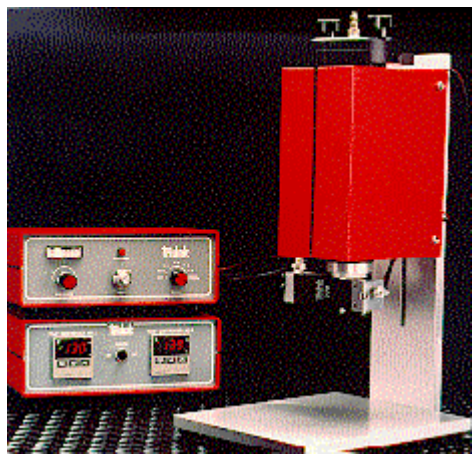
**Typical Characteristics:**

<b>Thermal Characteristics</b>	<b>Units</b>	<b>Hot Melt 71°C</b>
Overall Thermal Resistance at 10psi. See graph of Thermal Resistance vs Closure Force	°C/W/in <sup>2</sup>	0.03
Thermal Conductivity of Hot Melt Compound	W/m <sup>2</sup> .K	0.063
Specific Heat of Hot Melt	Cp	1801.6
Phase Change Temperature	°C	71
Use Temperature	°C	-60 to +200
<b>Mechanical Characteristics</b>	<b>Units</b>	<b>Hot Melt 71°C</b>
Standard Wafers	Pounds (Gram)	1 (454)
Viscosity (Hot Melt compound) at 150°C	Poise	>100
Density of Hot Melt Compound	g/cc	2.1
<b>Electrical Characteristics</b>	<b>Units</b>	<b>Hot Melt 71°C</b>
Volume Resistivity*	? -cm	10 <sup>14</sup>
*Note: This material is not electrically conductive but contains nothing to prevent metal-to-metal contact when a component is pressed onto a heat sink.		



**Thermal Resistance versus Closure Force**

**How to Use:**

	<p>Use standard Hot Melt dispensing equipment to create dots, stripes, or any other required pattern. Immediately after application of "Tacky2", while it is still molten, you can press components onto the compound. They have sufficient "green strength" to hold the components until the compound returns to the solid state. The adhesive strength of the resulting thermoplastic bond will be &gt;25psi. You can also let the "Tacky2" return to the solid state. It will be naturally tacky. You can press components down into the solidified</p>
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	compound to temporarily adhere them in place.
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### **Product Availability**

Available in Wafers and Blocks for use in Hot Melt Equipment. See specifics in "Product Availability"